

Electronic Patent Application Fee Transmittal

Application Number:	09538684			
Filing Date:	30-Mar-2000			
Title of Invention:	Varied-thickness heat sink for integrated circuit (ic) package			
First Named Inventor/Applicant Name:	Larry D. Kinsman			
Filer:	James R. Duzan/Leta Howard			
Attorney Docket Number:	3056.1US (96-803.1)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180